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TIDA-01493 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	C1	1	10uF	C1608X6S1A106M080AC	TDK	CAP, CERM, 10 µF, 10 V, +/- 10%, X6S, 0603	0603
2	C2, C3	2	1uF	GRM185C80J105KE26D	MuRata	CAP, CERM, 1 µF, 6.3 V, +/- 10%, X6S, 0603	0603
3	C4	1	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1µF, 50V, +/-10%, X7R, 0603	0603
4	C5	1	0.01uF	0603ZC103KAT2A	AVX	CAP, CERM, 0.01 µF, 10 V, +/- 10%, X7R, 0603	0603
5	C6	1	10uF	GRM188R6YA106MA73	Nichicon	CAP, CERM, 10 µF, 35 V, +/- 20%, X5R, 0603	0603
6	C7	1	100pF	C0603C101J5GAC	Kemet	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0603	0603
7	C8	1	10uF	GRM21BR6YA106KE43L	MuRata	CAP, CERM, 10 µF, 35 V, +/- 10%, X5R, 0805	0805
8	J1, J2	2		TSW-101-07-G-S	Samtec	Header, 100mil, 1pos, Gold, TH	Testpoint
9	L1	1	47uH	CB2518T470K	Taiyo Yuden	Inductor, Wirewound, Ferrite, 47 µH, 0.11 A, 1.235 ohm, SMD	2.5x1.8x1.8mm
10	R1, R2, R3	3	4.75k	CRCW06034K75FKEA	Vishay-Dale	RES, 4.75k ohm, 1%, 0.1W, 0603	0603
11	U1	1		DRV10987PWPR	Texas Instruments	12- to 24-V, Three-Phase, Sensorless BLDC Motor Driver, PWP0024B (TSSOP-24)	PWP0024B
12	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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